

# MURF1620CT

Preferred Device

## SWITCHMODE™ Power Rectifier

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

### Features

- Ultrafast 35 Nanosecond Recovery Times
- 150°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- High Temperature Glass Passivated Junction
- Low Leakage Specified @ 150°C Case Temperature
- Current Derating @ Both Case and Ambient Temperatures
- Electrically Isolated. No Isolation Hardware Required.
- UL Recognized File #E69369 (Note 1)
- Pb-Free Package is Available\*

### Mechanical Characteristics:

- Case: Epoxy, Molded
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

### MAXIMUM RATINGS (Per Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{RWM}$ $V_R$	200	V
Average Rectified Forward Current Total Device, (Rated $V_R$ ), $T_C = 150^\circ\text{C}$ Total Device	$I_{F(AV)}$	8 16	A
Peak Repetitive Forward Current (Rated $V_R$ , Square Wave, 20 kHz), $T_C = 150^\circ\text{C}$	$I_{FM}$	16	A
Non-repetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	$I_{FSM}$	100	A
Operating Junction and Storage Temperature	$T_J, T_{stg}$	- 65 to +150	°C
RMS Isolation Voltage (t = 1 second, R.H. ≤ 30%, $T_A = 25^\circ\text{C}$ ) (Note 2) Per Figure 3 Per Figure 4 (Note 1) Per Figure 5	$V_{iso1}$ $V_{iso2}$ $V_{iso3}$	4500 3500 1500	V

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. UL Recognized mounting method is per Figure 4
2. Proper strike and creepage distance must be provided.

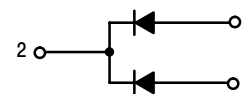
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



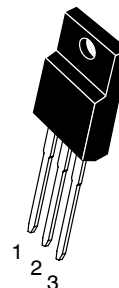
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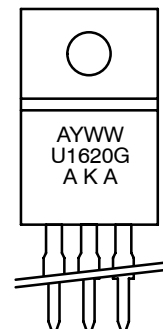
## ULTRAFAST RECTIFIER 16 AMPERES, 200 VOLTS



### MARKING DIAGRAM



ISOLATED TO-220  
CASE 221D  
STYLE 3



A = Assembly Location  
Y = Year  
WW = Work Week  
U1620 = Device Code  
G = Pb-Free Package  
AKA = Diode Polarity

### ORDERING INFORMATION

Device	Package	Shipping
MURF1620CT	TO-220	50 Units/Rail
MURF1620CTG	TO-220 (Pb-Free)	50 Units/Rail

Preferred devices are recommended choices for future use and best overall value.

# MURF1620CT

## THERMAL CHARACTERISTICS (Per Leg)

Rating	Symbol	Value	Unit
Maximum Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	4.2	$^{\circ}C/W$
Lead Temperature for Soldering Purposes: 1/8" from the Case for 5 seconds	$T_L$	260	$^{\circ}C$

## ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage (Note 3) ( $i_F = 8.0\text{ A}$ , $T_C = 150^{\circ}C$ ) ( $i_F = 8.0\text{ A}$ , $T_C = 25^{\circ}C$ )	$v_F$	0.895 0.975	V
Maximum Instantaneous Reverse Current (Note 3) (Rated DC Voltage, $T_C = 150^{\circ}C$ ) (Rated DC Voltage, $T_C = 25^{\circ}C$ )	$i_R$	250 5.0	$\mu A$
Maximum Reverse Recovery Time ( $I_F = 1.0\text{ A}$ , $di/dt = 50\text{ A}/\mu s$ ) ( $I_F = 0.5\text{ A}$ , $i_R = 1.0\text{ A}$ , $I_{REC} = 0.25\text{ A}$ )	$t_{rr}$	35 25	ns

3. Pulse Test: Pulse Width = 300  $\mu s$ , Duty Cycle  $\leq 2.0\%$ .

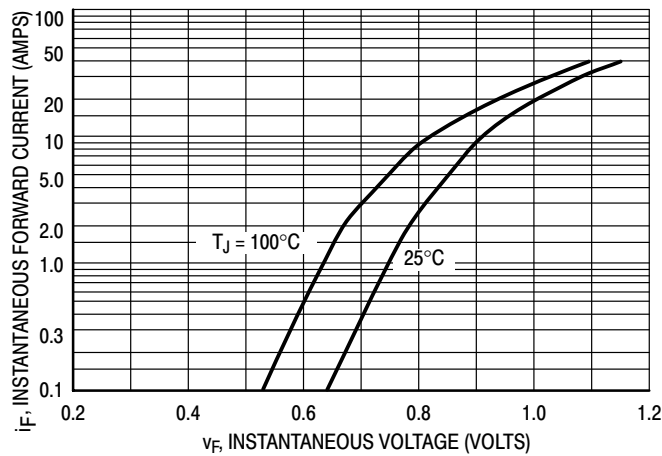


Figure 1. Typical Forward Voltage, Per Leg

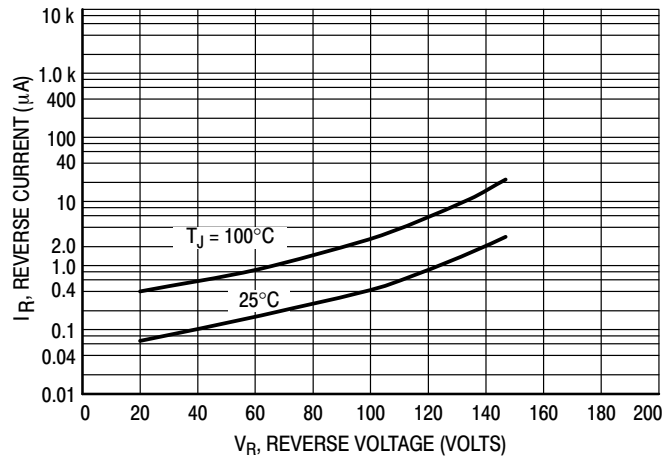
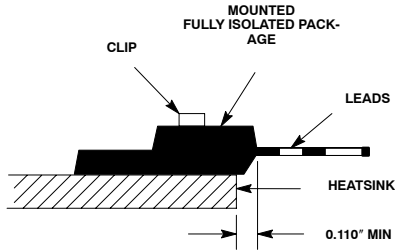


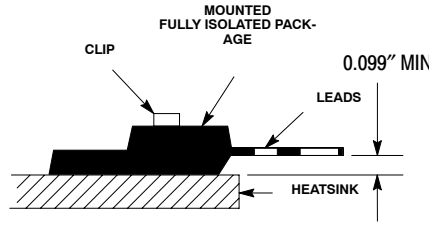
Figure 2. Typical Reverse Current, Per Leg\*

# MURF1620CT

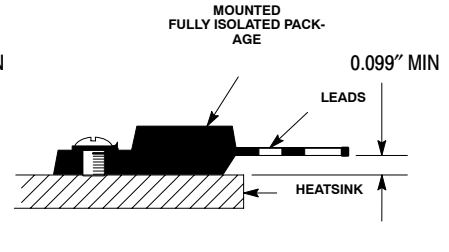
## TEST CONDITIONS FOR ISOLATION TESTS\*



**Figure 3. Clip Mounting Position for Isolation Test Number 1**



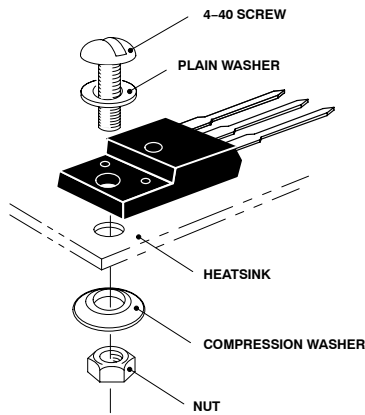
**Figure 4. Clip Mounting Position for Isolation Test Number 2**



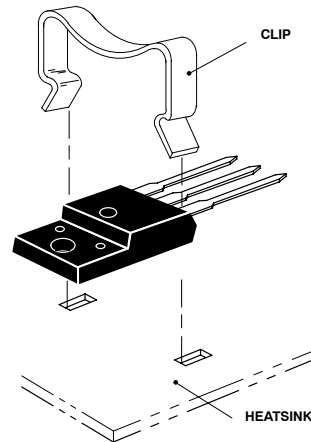
**Figure 5. Screw Mounting Position for Isolation Test Number 3**

\* Measurement made between leads and heatsink with all leads shorted together.

## MOUNTING INFORMATION\*\*



**6a. Screw-Mounted**



**6b. Clip-Mounted**

**Figure 6. Typical Mounting Techniques**

Laboratory tests on a limited number of samples indicate, when using the screw and compression washer mounting technique, a screw torque of 6 to 8 in · lbs is sufficient to provide maximum power dissipation capability. The compression washer helps to maintain a constant pressure on the package over time and during large temperature excursions.

Destructive laboratory tests show that using a hex head 4-40 screw, without washers, and applying a torque in excess of 20 in · lbs will cause the plastic to crack around the mounting hole, resulting in a loss of isolation capability.

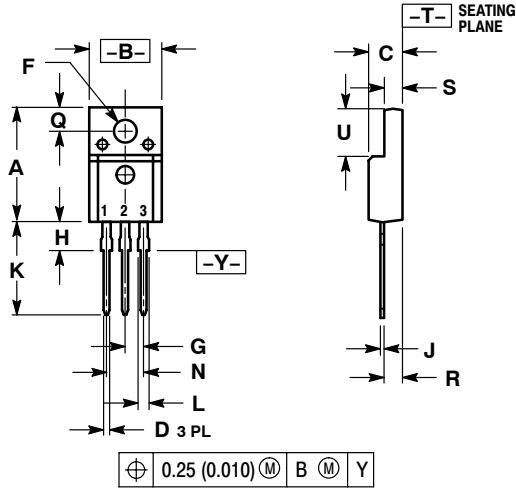
Additional tests on slotted 4-40 screws indicate that the screw slot fails between 15 to 20 in · lbs without adversely affecting the package. However, in order to positively ensure the package integrity of the fully isolated device, ON Semiconductor does not recommend exceeding 10 in · lbs of mounting torque under any mounting conditions.

\*\*For more information about mounting power semiconductors see Application Note AN1040.

# MURF1620CT

## PACKAGE DIMENSIONS

### TO-220 FULLPAK TRANSISTOR CASE 221D-03 ISSUE G



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH
3. 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.625	0.635	15.88	16.12
B	0.408	0.418	10.37	10.63
C	0.180	0.190	4.57	4.83
D	0.026	0.031	0.65	0.78
F	0.116	0.119	2.95	3.02
G	0.100 BSC		2.54 BSC	
H	0.125	0.135	3.18	3.43
J	0.018	0.025	0.45	0.63
K	0.530	0.540	13.47	13.73
L	0.048	0.053	1.23	1.36
N	0.200 BSC		5.08 BSC	
Q	0.124	0.128	3.15	3.25
R	0.099	0.103	2.51	2.62
S	0.101	0.113	2.57	2.87
U	0.238	0.258	6.06	6.56

**STYLE 3:**

- PIN 1. ANODE
2. CATHODE
3. ANODE

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